

**Amendments to the Specification:**

Please amend the specification as follows:

[0016] The substrate 202 includes an odd number of PCB layers in which the middle PCB layer comprises a layer of an electrically conductive material, such as heavy copper (for example, 4 ounces per square inch). The layer of electrically conductive material protrudes [[form]] from the sides of the substrate 202 to form connectors 204. For illustration purposes, the connectors 204 may be further plated with Tin/Nickel to form desired IC package pins. The thickness of the connectors 204 should be compatible with conventional lead frames, i.e. between 4 and 8 mils. FIG. 2 illustrates a TSOP package between the substrate 202 and the main board 206.

[0018] Furthermore, the substrate 202 may also be able to accommodate other IC packaging modules such as a TSOP device 216 coupled to the top surface 208 of the substrate 202, and another TSOP device 218 coupled to the bottom surface 210 of the substrate 202. The substrate 202 may thus be able to receive modules of various packaging types. Therefore several different modules may be packaged into a single IC form that would later be piggybacked onto the main board 206 or onto another module (not shown). This would result in reducing the main ~~board~~ board's 206 X and Y directions and add a Z dimension instead.

[0020] The electrically conductive layers 310, 312, 316, 318, and 326 may form conductive traces that communicate with modules that are later mounted on either sides of the substrate 302[[:]]; the top surface 310 of the top PCB layer 304 and the bottom surface 318 of the bottom PCB layer 308. [[Thus]] Thus, both sides of the substrate 302 may be utilized for chip or

component placement and can be built in different packages such as TSOP, SOIC, QFP, etc. The substrate 302 may thus act as an interface PCB between the modules the substrate 302 receives and a main board on which the substrate 302 is coupled to.

[0022] The multilayer PCB may include several PCB ~~layer~~ layers with a middle layer being electrically conductive. The electrically conductive middle layer protrudes from the sides of the multiplayer PCB to form connectors, such as pins, that will interface with another module or the main board.